

Final Product/Process Change Notification

Document #:FPCN22966ZS Issue Date: 14 Dec 2021

| Title of Change: | Wafer Fab Capacity Expansion for Trench 6 MOSFET Technology at Global Foundries in New York, US. | | |
|--|---|--|--|
| Proposed Changed Material First Ship Date: | 14 Jun 2022 or earlier if approved by customer | | |
| Current Material Last Order Date: | 05 May 2022 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability. | | |
| Current Material Last Delivery Date: | 13 Jun 2022 The Current Material Last Delivery Date may be subject to change based on build and depletion of current (unchanged) material inventory | | |
| Product Category: | Active components – Discrete components | | |
| Contact information: | Contact your local onsemi Sales Office or <u>Ammar.Anuar@onsemi.com</u> | | |
| PCN Samples Contact: | Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. | | |
| Sample Availability Date: 17 Dec 2021 | | | |
| PPAP Availability Date: 17 Dec 2021 | | | |
| Additional Reliability Data: | Contact your local onsemi Sales Office or Robert.Baran@onsemi.com | | |
| Type of Notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com . | | |
| Change Category | | | |
| Category | Type of Change | | |
| Test Flow | Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor | | |
| Process - Wafer Production | Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter | | |

Description and Purpose:

This Product Change Notification, is the continuation from FPCN22966ZI, which is intended to increase capacity for onsemi automotive 30V and 40V Trench 6 MOSFET technology products by transferring wafer fabrication for these products to the Global Foundries Fab located in New York, US.

The changes include transferring wafer fabrication, back grind and back metal, to Global Foundries, and utilizing 300mm instead of 200mm diameter wafers. And while the assembly location remains unchanged (at onsemi, Seremban, Malaysia), wafer saw and die attach tooling are being updated to accommodate 300mm wafers.

There is no change to the orderable part number.

There is no product marking change as a result of this change.

| | Before Change | After Change |
|-----------------------------|------------------------|--------------------------|
| Wafer Fabrication Site | onsemi Aizu, Japan | Global Foundries, US |
| Wafer Diameter | 200mm (existing sites) | 300mm (Global Foundries) |
| Wafer Probe Site | onsemi, Malaysia | Global Foundries, US |
| Back Grind, Back Metal Site | onsemi ISMF, Malaysia | Global Foundries, US |

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| Reason / Motivation for Change: | Source/Supply/Capacity Changes Process/Materials Change |
|--|---|
| Anticipated impact on fit, form, function, reliability, product safety or manufacturability: | The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts. |
| Sites Affected: | |

onsemi SitesExternal Foundry/Subcon Sitesonsemi Aizu, JapanGlobal Foundries East Fishkill, New York, United Statesonsemi Seremban, Malaysiaonsemi, ISMF Malaysia

Marking of Parts/ Traceability of Change:

Material will be traceable with ONs lot trace code & tracking

Reliability Data Summary:

QV DEVICE NAME (DIE QUAL) NVMFS5C404N

RMS: 66099, 67744, 67566, 67567

PACKAGE: SO8FL-HE

| Test | Specification | Condition | Interval | Results |
|-------|------------------------------------|---|-----------|---------|
| HTRB | JESD22-A108 | Ta=175°C, 100% max rated Vds | 2016 hrs | 0/231 |
| HTGB | JESD22-A108 | Ta=175°C, 100% max rated Vgss | 2016 hrs | 0/231 |
| HTSL | JESD22-A103 | Ta= 175°C | 2016 hrs | 0/231 |
| IOL | MIL-STD-750 (M1037) AEC-Q101 | Ta=+25°C, delta Tj=100°C On/off =2 min | 30000 cyc | 0/231 |
| TC | JESD22-A104 | Ta= -55°C to +150°C | 1000 cyc | 0/231 |
| HAST | JESD22-A110 | 130°C, 85% RH, 18.8psig, bias | 192 hrs | 0/231 |
| uHAST | JESD22-A118 | 130°C, 85% RH, 18.8psig, unbiased | 96 hrs | 0/231 |
| PC | J-STD-020 JESD-A113 | MSL1 @ 260°C | | |
| RSH | JESD22- B106 | Ta = 265C, 10 sec | | 0/30 |

QV DEVICE NAME (DIE QUAL): NVMFS5C404N

RMS: 66100 PACKAGE: SO8FL-HE

| | Test | Specification | Condition | Interval | Results |
|---|------|---------------|-------------------------------|----------|---------|
| ĺ | HTGB | JESD22-A108 | Ta=175°C, 100% max rated Vgss | 2016 hrs | 0/231 |

NOTE AEC-1 pager is attached.

To view attachments:

1.Download pdf copy of the PCN to your computer

2.Open the downloaded pdf copy of the PCN

3.Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field

4. Then click on the attached file/s.

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| Electrical Characteristics Summary: | |
|--|--|
| | |

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

| Current Part Number | New Part Number | Qualification Vehicle | |
|---------------------|-----------------|-------------------------------------|--|
| NVTFS004N04CTAG | NA | NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K | |
| NVMFS5C420NT1G | NA | NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K | |
| NVMFS5C406NT1G | NA | NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K | |
| NVMFS4C306NT1G | NA | NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K | |

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Appendix A: Changed Products

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| Product | Customer Part Number | Qualification Vehicle | New Part Number | Replacement Supplier |
|----------------|----------------------|--|-----------------|----------------------|
| NVMFS5C420NT1G | | NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K | NA | |